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(54) COMPOSITE PRINTED WIRING BOARD

(57) Abstract:

PURPOSE: To furnish a composite printed wiring board enabling improvement of the reliability in connection with an electronic component and prevention of a damage on the electronic component, by making the thermal expansion coefficient of the whole of the board approximate to the thermal expansion coefficient of a semiconductor integrated circuit TSO or a bare chip IC.

CONSTITUTION: In a printed wiring board having a composite insulating material layer 13 prepared by impregnating pore spaces of porous ceramic or porous glass solvent-welded on the rear of a copper leaf 12, with thermosetting resin, a base plate 11 prepared by impregnating the pore spaces of porous ceramic with the thermosetting resin and the composite insulating material layer 13 are

laminated by a prepreg 14.

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